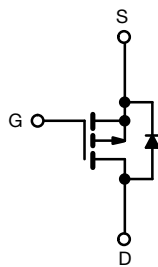
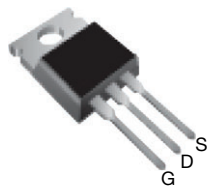


Power MOSFET

TO-220AB


P-Channel MOSFET

PRODUCT SUMMARY

V_{DS} (V)	-200	
$R_{DS(on)}$ max. (Ω)	$V_{GS} = -10$ V	0.80
Q_g max. (nC)	29	
Q_{gs} (nC)	5.4	
Q_{gd} (nC)	15	
Configuration	Single	

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- P-channel
- Fast switching
- Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS*
Available

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free	IRF9630PbF
Lead (Pb)-free and halogen-free	IRF9630PbF-BE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	-200	V
Gate-source voltage			V_{GS}	± 20	
Continuous drain current	V_{GS} at 10 V	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	-6.5	A
		$T_C = 100\text{ }^{\circ}\text{C}$		-4.0	
Pulsed drain current ^a			I_{DM}	-26	
Linear derating factor				0.59	W/ $^{\circ}\text{C}$
Single pulse avalanche energy ^b			E_{AS}	500	mJ
Repetitive avalanche current ^a			I_{AR}	-6.4	A
Repetitive avalanche energy ^a			E_{AR}	7.4	mJ
Maximum power dissipation	$T_C = 25\text{ }^{\circ}\text{C}$		P_D	74	W
Peak diode recovery dV/dt ^c			dV/dt	-5.0	V/ns
Operating junction and storage temperature range			T_J, T_{stg}	-55 to +150	$^{\circ}\text{C}$
Soldering recommendations (peak temperature) ^d	For 10 s			300	
Mounting torque	6-32 or M3 screw			10	lbf · in
				1.1	N · m

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. $V_{DD} = -50$ V, starting $T_J = 25^\circ\text{C}$, $L = 17$ mH, $R_g = 25\ \Omega$, $I_{AS} = -6.5$ A (see fig. 12)

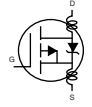
c. $I_{SD} \leq -6.5$ A, $dI/dt \leq 120$ A/ μs , $V_{DD} \leq V_{DS}$, $T_J \leq 150^\circ\text{C}$

d. 1.6 mm from case

THERMAL RESISTANCE RATINGS

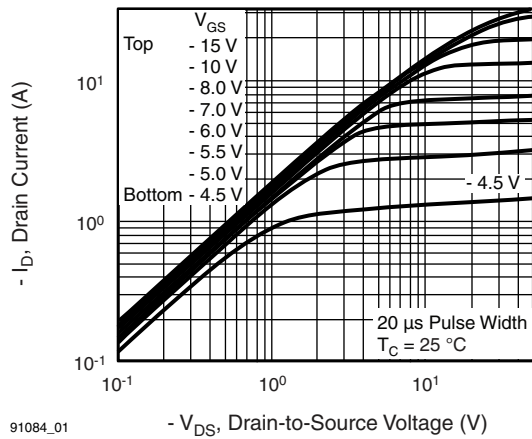
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W
Case-to-sink, flat, greased surface	R_{thCS}	0.50	-	
Maximum junction-to-case (drain)	R_{thJC}	-	1.7	

SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

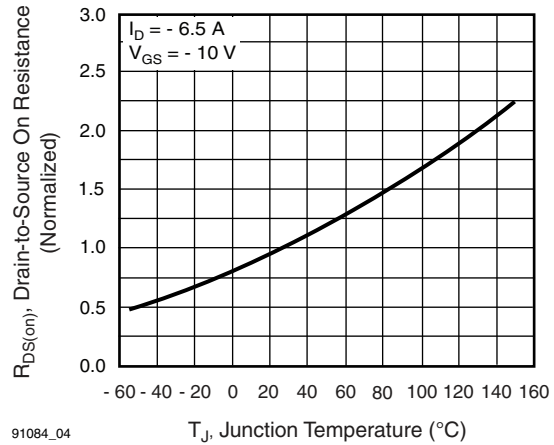
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = -250\text{ }\mu\text{A}$	-200	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^{\circ}\text{C}$, $I_D = -1\text{ mA}$	-	-0.24	-	V/°C
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250\text{ }\mu\text{A}$	-2.0	-	-4.0	V
Gate-source leakage	I_{GSS}	$V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -200\text{ V}$, $V_{GS} = 0\text{ V}$	-	-	-100	μA
		$V_{DS} = -160\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	-	-500	
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$, $I_D = -3.9\text{ A}^b$	-	-	0.80	Ω
Forward transconductance	g_{fs}	$V_{DS} = -50\text{ V}$, $I_D = -3.9\text{ A}^b$	2.8	-	-	S
Dynamic						
Input capacitance	C_{iss}	$V_{GS} = 0\text{ V}$, $V_{DS} = -25\text{ V}$, $f = 1.0\text{ MHz}$, see fig. 5	-	700	-	pF
Output capacitance	C_{oss}		-	200	-	
Reverse transfer capacitance	C_{rss}		-	40	-	
Total gate charge	Q_g	$V_{GS} = -10\text{ V}$, $I_D = -6.5\text{ A}$, $V_{DS} = -160\text{ V}$, see fig. 6 and 13 ^b	-	-	29	nC
Gate-source charge	Q_{gs}		-	-	5.4	
Gate-drain charge	Q_{gd}		-	-	15	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -100\text{ V}$, $I_D = -6.5\text{ A}$, $R_g = 12\text{ }\Omega$, $R_D = 15\text{ }\Omega$, see fig. 10 ^b	-	12	-	ns
Rise time	t_r		-	27	-	
Turn-off delay time	$t_{d(off)}$		-	28	-	
Fall time	t_f		-	24	-	
Gate input resistance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 	-	4.5	-	nH
Internal drain inductance	L_S		-	7.5	-	
Internal source inductance	R_g	$f = 1\text{ MHz}$, open drain	0.6	-	3.7	Ω
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p-n junction diode 	-	-	-6.5	A
Pulsed diode forward current ^a	I_{SM}		-	-	-26	
Body diode voltage	V_{SD}	$T_J = 25\text{ }^{\circ}\text{C}$, $I_S = -6.5\text{ A}$, $V_{GS} = 0\text{ V}^b$	-	-	-6.5	V
Body diode reverse recovery time	t_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$, $I_F = -6.5\text{ A}$, $dI/dt = 100\text{ A}/\mu\text{s}^b$	-	200	300	ns
Body diode reverse recovery charge	Q_{rr}		-	1.9	2.9	μC
Forward turn-on time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

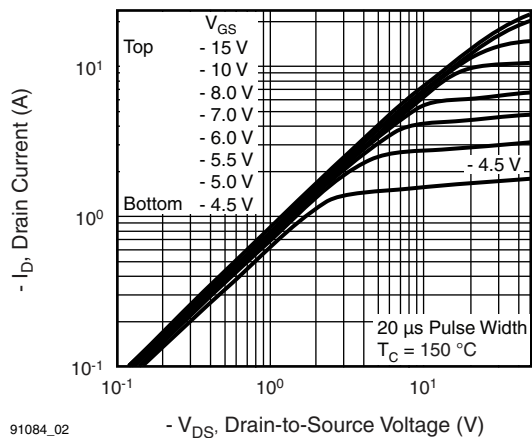
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


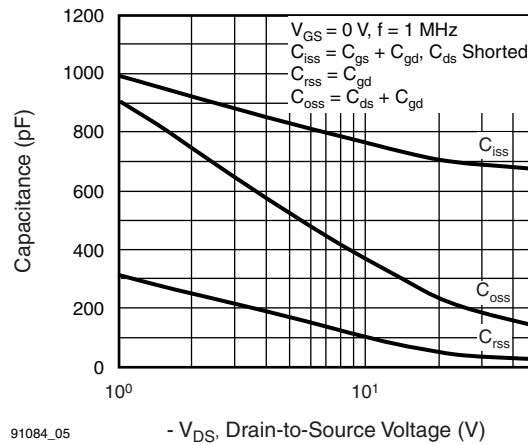
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Fig. 1 - Typical Output Characteristics, $T_C = 25^\circ\text{C}$


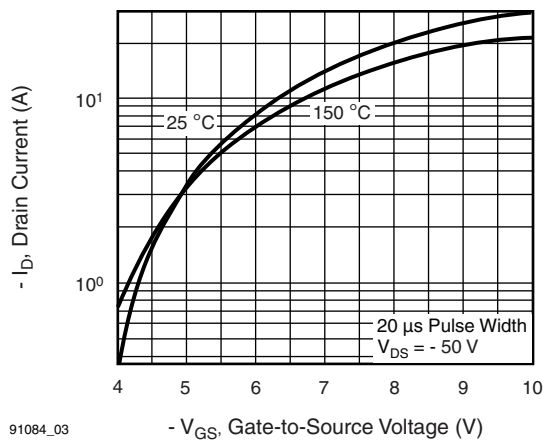
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Fig. 4 - Normalized On-Resistance vs. Temperature


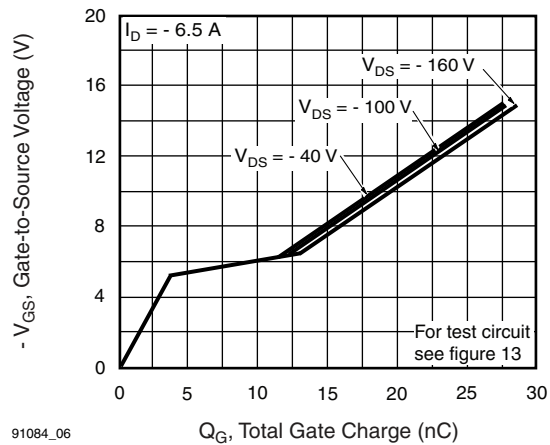
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Fig. 2 - Typical Output Characteristics, $T_C = 150^\circ\text{C}$


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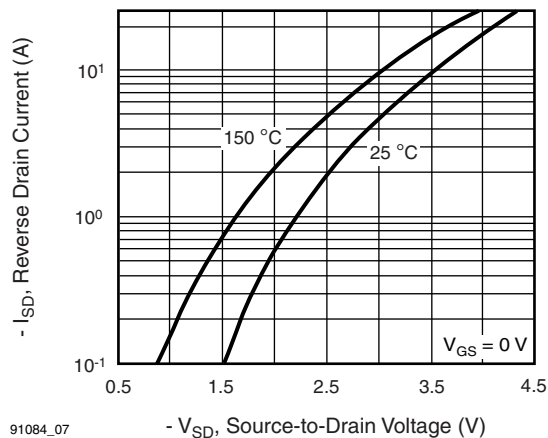
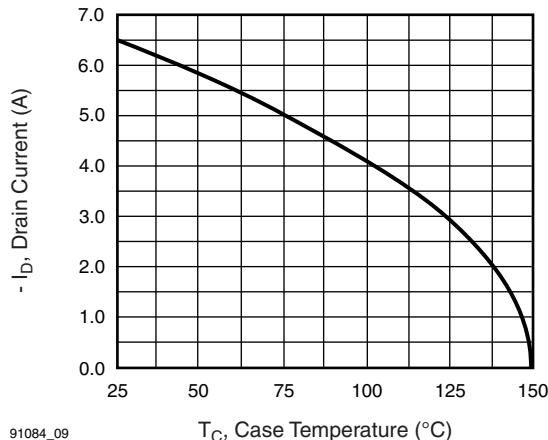
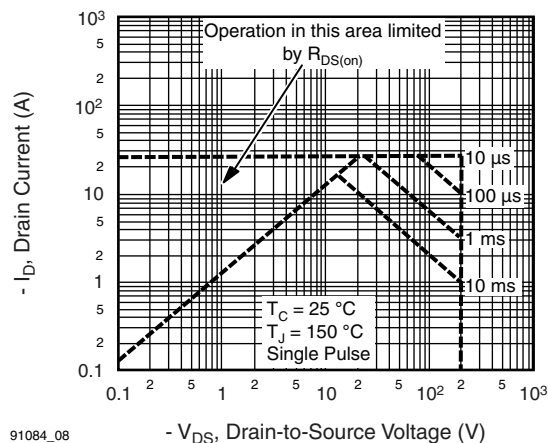
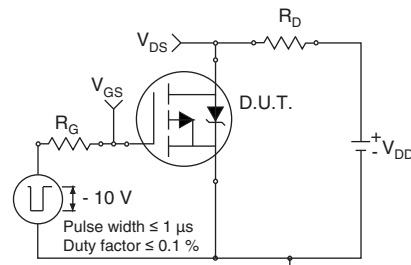
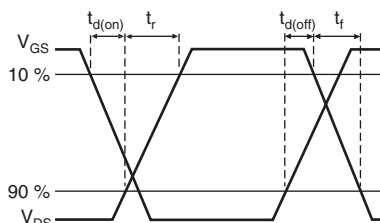
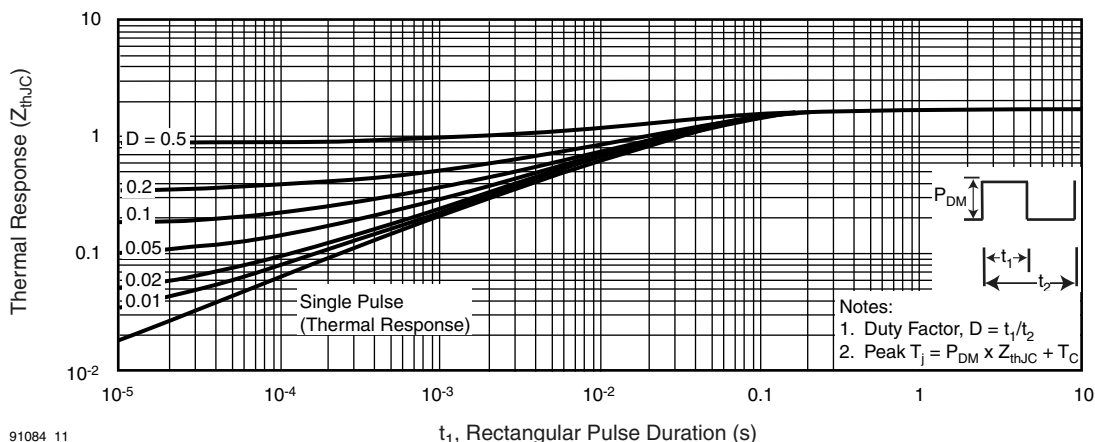
Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage


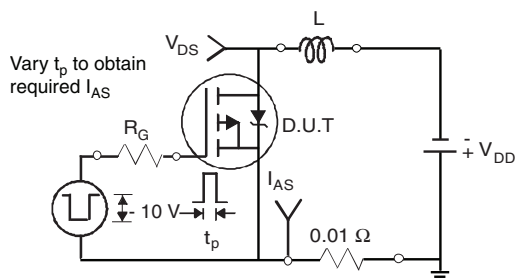
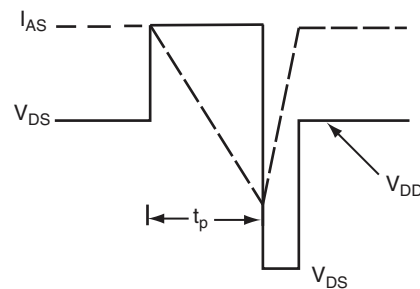
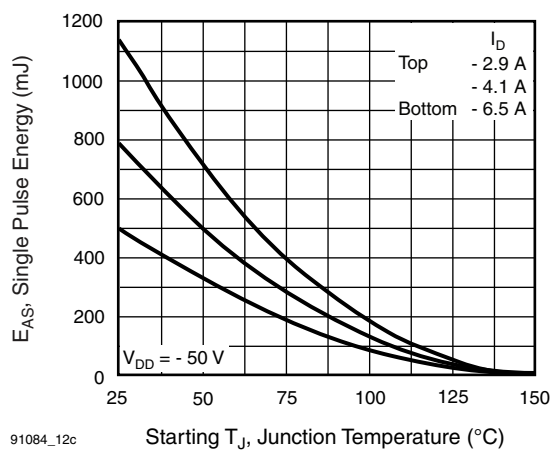
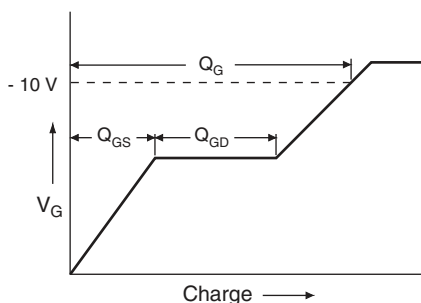
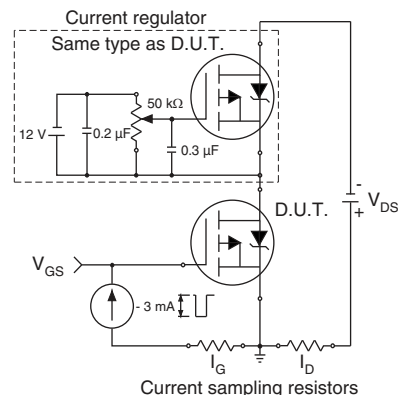
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Fig. 3 - Typical Transfer Characteristics


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Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage


Fig. 7 - Typical Source-Drain Diode Forward Voltage

Fig. 9 - Maximum Drain Current vs. Case Temperature

Fig. 8 - Maximum Safe Operating Area

Fig. 10a - Switching Time Test Circuit

Fig. 10b - Switching Time Waveforms

Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case


Fig. 12a - Unclamped Inductive Test Circuit

Fig. 12b - Unclamped Inductive Waveforms

Fig. 12c - Maximum Avalanche Energy vs. Drain Current

Fig. 13a - Basic Gate Charge Waveform

Fig. 13c - Gate Charge Test Circuit

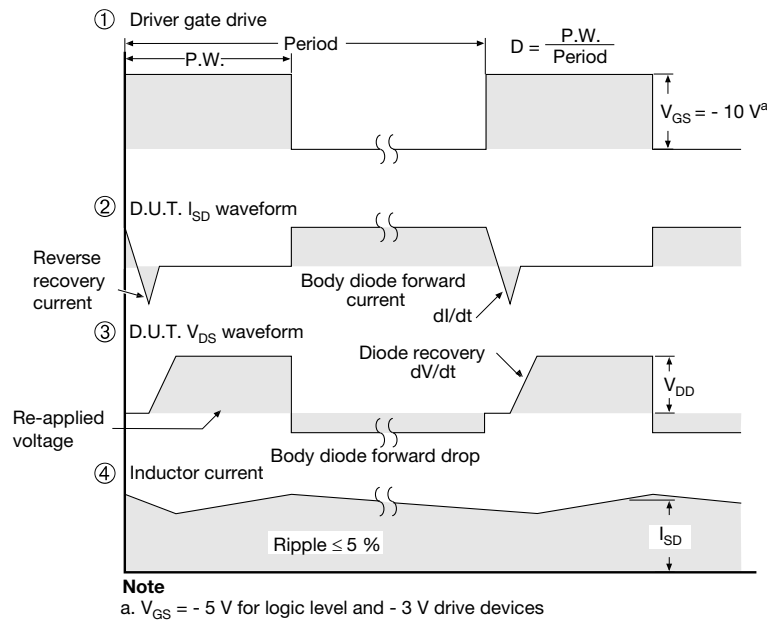
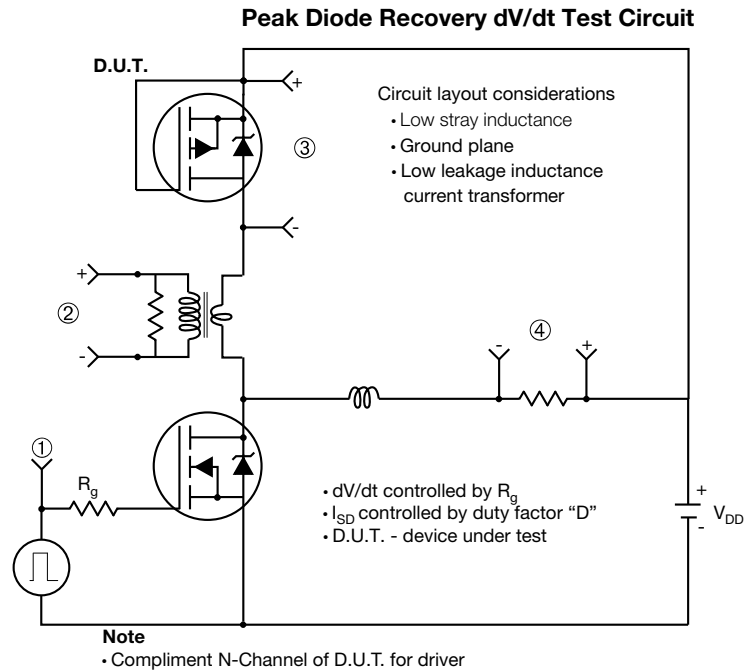


Fig. 14 - For P-Channel

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